



## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10B332KB8NNWC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 3.3nF, 50V, ±10%, X7R, 0603

## A. Samsung Part Number

<u>CL</u> <u>10</u> <u>B</u> <u>332</u> <u>K</u> <u>B</u> <u>8</u> <u>N</u> <u>N</u> <u>W</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor							
2	Size	0603 (inch c	ode)	L: 1.	6 ± 0.1	mm	W:	0.8 ± 0.1	mm
3	Dielectric	X7R		(8	) Inner e	electrode	N	li	
4	Capacitance	3.3 nF			Termir	nation	C	Cu	
(5)	Capacitance	±10 %			Plating	<b>j</b>	S	Sn 100%	(Pb Free)
	tolerance			9	Produ	ct	N	lormal	
6	Rated Voltage	50 V		Œ	Specia	ıl	P	roduct for N	letwork application
7	Thickness	$0.8 \pm 0.1$	mm	11	Packa	ging	C	Cardboard T	ype,7"reel(4,000ea)

## **B. Samsung Reliability Test and Judgement condition**

	Performance	Test condition					
Capacitance	Within specified tolerance	1kHz±10% 1.0±0.2Vrms					
Tan δ (DF)	0.025 max.						
Insulation	More than 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.					
Resistance							
Appearance	No abnormal exterior appearance	Visual inspection					
Withstanding	No dielectric breakdown or	250% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	X7R						
Characteristics	(From -55℃ to 125℃, Capacitance change should be within ±15%)						
Adhesive Strength	No peeling shall be occur on the	500g⋅F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)					
		with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5℃, 3±0.3sec.					
		(preheating : 80~120℃ for 10~30sec.)					
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5°C, 10±1sec.					
Soldering heat	Tan δ, IR : initial spec.	1001d01 pot : 27 020 0 ; 102 1000.					

	Performance	Test condition				
Vibration Test	Capacitance change: within ±5%	Amplitude : 1.5mm				
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)				
		2hours × 3 direction (x, y, z)				
Moisture	Capacitance change: within ±12.5%	With rated voltage				
Resistance	Tan δ : 0.05 max	40±2℃, 90~95%RH, 500+12/-0 hours.				
	IR : More than 25MΩ· <i>μ</i> F					
High Temperature	Capacitance change: within ±12.5%	With 200% of the rated voltage				
Resistance	Tan δ : 0.05 max	Max. operating temperature				
	IR : More than 50MΩ·μF					
		1000+48/-0 hours.				
Temperature	Capacitance change: within ±7.5%	1 cycle condition				
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25°C				
		→ Max. operating temperature → 25°C				
		5 cycles test.				

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}$ C , 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.